

**PATENT APPLICATION**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of Docket No: Q79703

Hisayuki MIKI, et al.

Appln. No.: 10/586,849 Group Art Unit: 2811

Confirmation No.: 3462 Examiner: Unknown

Filed: July 20, 2006

For: **GALLIUM NITRIDE-BASED COMPOUND SEMICONDUCTOR MULTILAYER STRUCTURE AND PRODUCTION METHOD THEREOF**

**REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT**

ATTN: Office of Initial Patent Examination  
Filing Receipt Correction  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

We enclose a copy of the Official Filing Receipt for the above-identified application and request the following correction:

**Assignment for Published Patent Application**

**SHOWA DENKO K.K.**

Verification for the requested correction is indicated on the Executed Assignment Document filed July 20, 2006.

Respectfully submitted,



\_\_\_\_\_  
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WASHINGTON OFFICE  
**23373**  
CUSTOMER NUMBER

Date: April 24, 2007



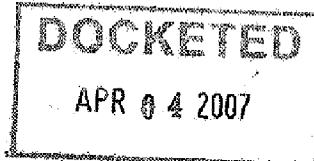
## UNITED STATES PATENT AND TRADEMARK OFFICE

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APPL NO.	FILING OR 371(c) DATE	ART UNIT	FIL FEE REC'D	ATTY/DOCKET NO	TOT CLMS	IND CLMS
10/586,849	07/20/2006	2811	1750	Q79703	37	2

## CONFIRMATION NO. 3462

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## FILING RECEIPT



\*OC000000023131830\*

Date Mailed: 03/30/2007

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

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ASSIGNMENT FOR PUBLISHED PATENT APPLICATION SHOWA DENKO K.K.

Power of Attorney: The patent practitioners associated with Customer Number 23373.

## Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP05/01642 01/28/2005  
 which claims benefit of 60/541,069 02/03/2004

## Foreign Applications

JAPAN 2004-021479 01/29/2004

If Required, Foreign Filing License Granted: 03/27/2007

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is US10/586,849

Projected Publication Date: 07/05/2007

Non-Publication Request: No

## U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

(Insert  
ASSIGNEE's  
Name(s)  
Address(es))

SHOWA DENKO K.K.

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(Title of  
Invention)

**GALLIUM NITRIDE-BASED COMPOUND SEMICONDUCTOR MULTILAYER STRUCTURE  
AND PRODUCTION METHOD THEREOF**

relating to International Patent Application PCT/JP 2005\_001642 and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date  
of execution  
of application,  
if not  
concurrent)

(a) executed on \_\_\_\_\_:

(b) filed on \_\_\_\_\_:  
Serial No. \_\_\_\_\_

\_\_\_\_\_ is hereby authorized to insert in (b) the specified  
data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

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